

PCN Number:	20210722000.1	PCN Date:	August 03, 2021
Title:	Qualification of CFAB as an additional wafer fab site option for select LBC5 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Nov. 3, 2021	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Packing/Shipping/Labeling
		<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change

PCN Details

Description of Change:

This change notification is to announce the qualification of CFAB as an additional wafer fab site option for the LBC5 devices listed in the product affected section of this document.

Current Sites			Additional Sites		
Current Fab Site	Fab Process	Wafer Diameter	Additional Fab Site	Fab Process	Wafer Diameter
DP1DM5	LBC5	200 mm	CFAB	LBC5	200 mm

The LBC5 process technology has been running successfully in production at CFAB since 2012.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
CFAB	CU3	CHN	Chengdu

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT: 39
 ITEM:
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHP (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SN65HVD1794D	SN65HVD1794DR	SN65HVD1794P
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Qualification Report

Approve Date 29-Jun-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVD1794D	QBS Package Reference: TA5613APHD
-	ESD - HBM (All pins)	4000 V	1/3/0	-
AC	Autoclave 121C	96 Hours	-	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HBM	ESD - HBM (All pins)	4000 V	1/3/0	-
HBM	ESD - HBM (Bus Pins Only)	16000 V	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	-
HTOL	Life Test, 155C	240 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/230/0
LU	Latch-up	(Per JESD78)	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0

- QBS: Qual By Similarity

- Qual Device SN65HVD1794D is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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